

IGBT

TRENCHSTOP™ IGBT4 Low Power Chip  
IGC13T120T8L

Data Sheet

Industrial Power Control



## Table of Contents

Features and Applications.....	3
Mechanical Parameters.....	3
Maximum Ratings.....	4
Static and Electrical Characteristics .....	4
Further Electrical Characteristics .....	5
Chip Drawing.....	6
Revision History .....	7
Relevant Application Notes .....	7
Legal Disclaimer .....	8

## TRENCHSTOP™ IGBT4 Low Power Chip

### Features:

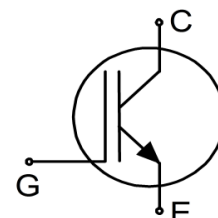
- 1200V trench & field stop technology
- Low switching losses
- Positive temperature coefficient
- Easy paralleling

### Recommended for:

- Low / medium power modules

### Applications:

- Low / medium power drives



Chip Type	$V_{CE}$	$I_{Cn}$	Die Size	Package
IGC13T120T8L	1200V	10A	3.54mm x 3.81mm	Sawn on foil

### Mechanical Parameters

Die size	3.54 x 3.81		mm <sup>2</sup>
Emitter pad size	See chip drawing		
Gate pad size	0.61 x 1.10		
Area total	13.49		
Silicon thickness	115		μm
Wafer size	200		mm
Maximum possible chips per wafer	2036		
Passivation frontside	Photoimide		
Pad metal	3200nm AlSiCu		
Backside metal	Ni Ag – system To achieve a reliable solder connection it is strongly recommended not to consume the Ni layer completely during production process		
Die bond	Electrically conductive epoxy glue and soft solder		
Wire bond	Al, ≤500μm		
Reject ink dot size	Ø 0.65mm; max. 1.2mm		
Storage environment (<6 months)	for original and sealed MBB bags	Ambient atmosphere air, temperature 17°C – 25°C	
	for open MBB bags	Acc. IEC 62258-3; Section 9.4 Storage Environment.	

## Maximum Ratings

In general, from reliability and lifetime point of view, the lower the operation junction temperature and/or the applied voltage, the greater the expected lifetime of any semiconductor device.

Parameter	Symbol	Value	Unit
Collector-emitter voltage, $T_{vj}=25^{\circ}\text{C}$	$V_{CE}$	1200	V
DC collector current, limited by $T_{vj\text{ max}}^1$	$I_C$	-	A
Pulsed collector current, $t_p$ limited by $T_{vj\text{ max}}^2$	$I_{C,puls}$	30	A
Gate-emitter voltage	$V_{GE}$	$\pm 20$	V
Junction temperature	$T_{vj}$	-40 ... +175	$^{\circ}\text{C}$
Operating junction temperature	$T_{vj\text{ op}}$	-40 ... +150	$^{\circ}\text{C}$
Short circuit data <sup>1/2/3</sup> $V_{GE}=15\text{V}$ , $V_{CC}=800\text{V}$ , $T_{vj}=150^{\circ}\text{C}$	$t_{sc}$	10	$\mu\text{s}$

## Static Characteristics (tested on wafer), $T_{vj}=25^{\circ}\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0\text{V}$ , $I_C=0.5\text{mA}$	1200	-	-	V
Collector-emitter saturation voltage	$V_{CEsat}$	$V_{GE}=15\text{V}$ , $I_C=10\text{A}$	1.58	1.85	2.07	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=0.35\text{mA}$ , $V_{GE}=V_{CE}$	5.3	5.8	6.3	
Zero gate voltage collector current	$I_{CES}$	$V_{CE}=1200\text{V}$ , $V_{GE}=0\text{V}$	-	-	1.2	$\mu\text{A}$
Gate-emitter leakage current	$I_{GES}$	$V_{CE}=0\text{V}$ , $V_{GE}=20\text{V}$	-	-	120	nA
Integrated gate resistor	$r_G$		none			$\Omega$

## Electrical Characteristics <sup>2</sup>

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Collector-emitter saturation voltage	$V_{CEsat}$	$V_{GE}=15\text{V}$ , $I_C=10\text{A}$ , $T_{vj}=150^{\circ}\text{C}$	-	2.25	-	V
Input capacitance	$C_{ies}$	$V_{CE}=25\text{V}$ , $V_{GE}=0\text{V}$ , $f=1\text{MHz}$	-	625	-	pF
Reverse transfer capacitance	$C_{res}$	$T_{vj}=25^{\circ}\text{C}$	-	40	-	

<sup>1</sup> Depending on thermal properties of assembly.

<sup>2</sup> Not subject to production test - verified by design/characterization.

<sup>3</sup> Allowed number of short circuits: <1000; time between short circuits: >1s.



# IGC13T120T8L

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## Further Electrical Characteristics

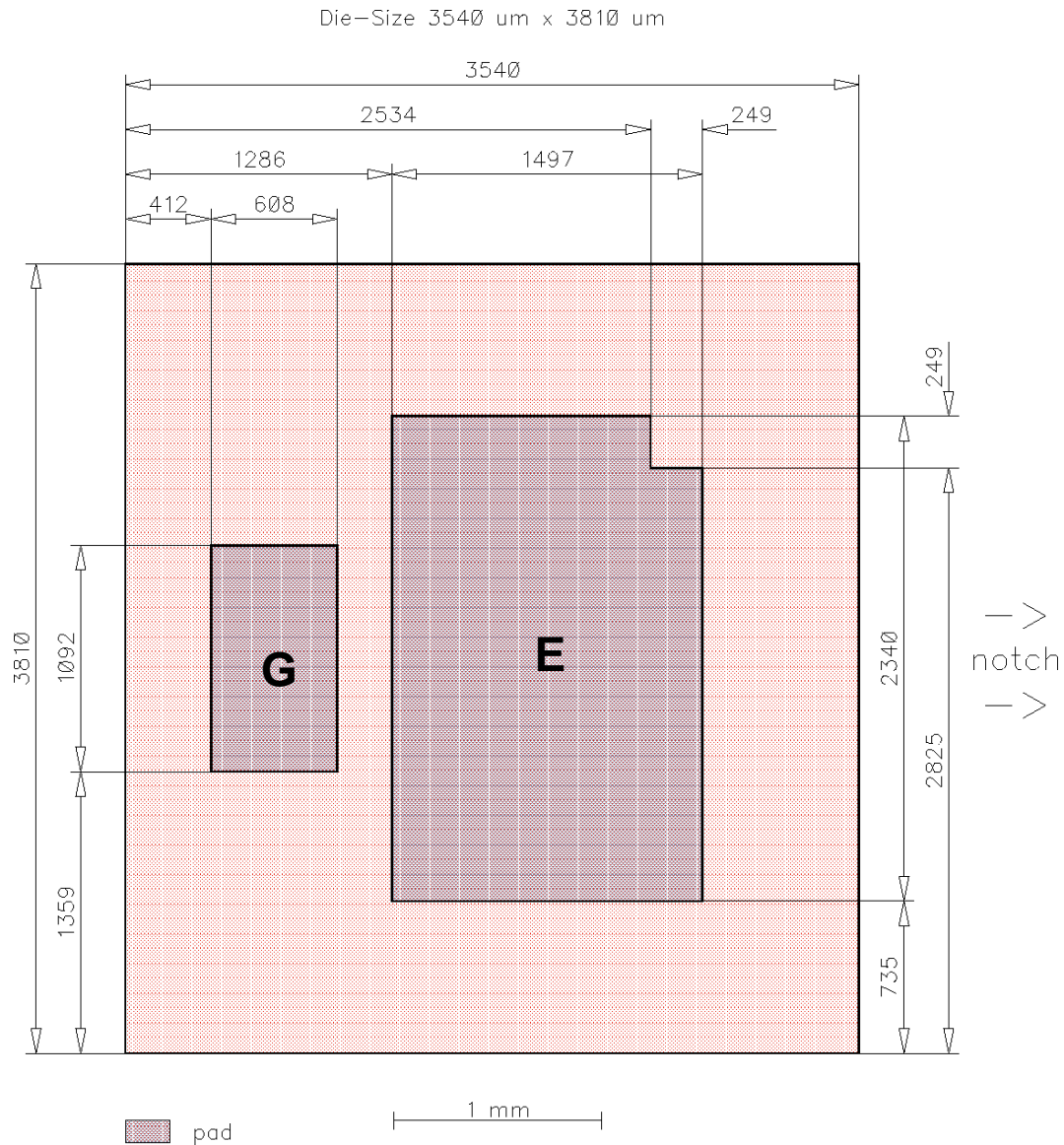
Switching characteristics and thermal properties are depending strongly on module design and mounting technology and can therefore not be specified for a bare die.

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Application example	FP10R12W1T4	Rev. 2.1
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## Chip Drawing



**E** = Emitter  
**G** = Gate



# IGC13T120T8L

## Bare Die Product Specifics

Test coverage at wafer level cannot cover all application conditions. Therefore it is recommended to test all characteristics which are relevant for the application at package level, including RBSOA and SCSOA.

## Description

AQL 0.65 for visual inspection according to failure catalogue

Electrostatic Discharge Sensitive Device according to MIL-STD 883

## Revision History

Revision	Subjects (major changes since last revision)	Date
2.0	Final data sheet	09.09.2016

## Relevant Application Notes

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**Infineon Technologies AG**  
**81726 München, Germany**  
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